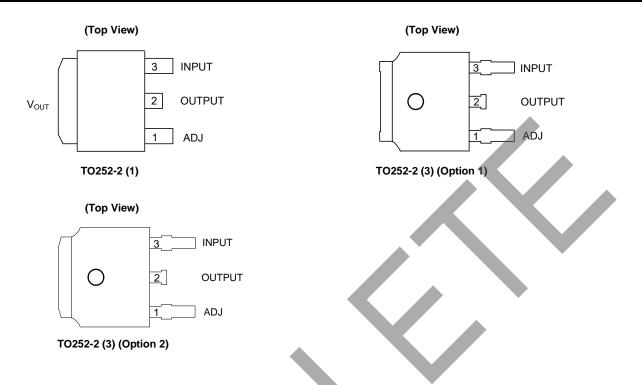
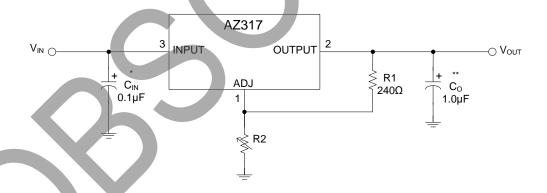


Pin Assignments (Cont.)



Typical Applications Circuit



 $^{^*}$ = C_{IN} is required if the regulator is located near power supply filter.

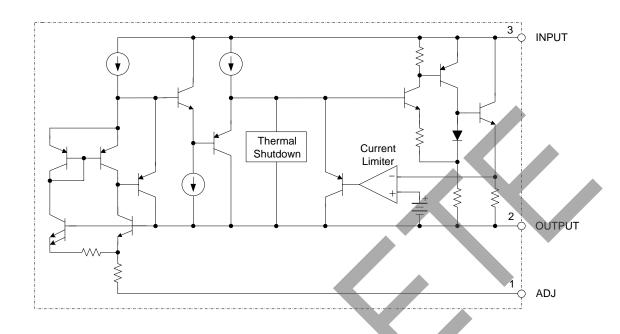
 $V_{OUT} = V_{REF} \times (1+R2/R1) + I_{ADJ} \times R2$

Since I_{ADJ} is controlled to less than $100\mu A$, the error associated with this term is negligible in most applications.

^{**=} C_O is needed for stability and it improves transient response.



Functional Block Diagram



Absolute Maximum Ratings (Note 4)

Symbol	Parameter	Value	Unit
V _{IN}	Input Voltage	20	V
TJ	Maximum Junction Temperature	+150	°C
Ts	Storage Temperature	-65 to +150	°C
T _{LEAD}	Lead Temperature (Soldering, 10sec)	+300	°C
ESD	ESD (Human Body Model)	4000	V

Note 4: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Unit
V _{IN}	Input Voltage	V _{OUT} +2	15	V
TJ	Operating Junction Temperature Range	0	+125	°C



Electrical Characteristics (Typicals and limits apply for T_J = +25°C, P ≤ Maximum Power Dissipation unless otherwise specified. Note 5)

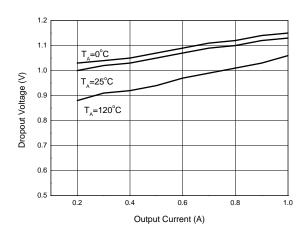
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{REF}	Reference Voltage	10mA ≤ I _{OUT} ≤ 1A, 3V ≤ (V _{IN} -V _{OUT}) ≤ 10V	1.20	1.25	1.30	V
S_V	Line Regulation	$I_{OUT} \le 20$ mA, $3V \le V_{IN}-V_{OUT} \le 10V$	_	0.01	0.04	%/V
Si	Load Regulation	V _{IN} -V _{OUT} = 2V, 10mA ≤ I _{OUT} ≤ 1A	_	0.2	0.4	%
_	Thermal Regulation	20ms Pulse	-/	0.04	0.07	%/W
ΔV	Dropout Voltage	I _{OUT} = 1A		1.2	1.3	V
I _{LIMIT}	Current Limit	(V _{IN} -V _{OUT}) = 2V	1.2	1.5	1.8	Α
_	Adjust Pin Current	_	_	50	100	μA
_	Adjust Pin Current Change	1.4V ≤ (V _{IN} -V _{OUT}) ≤ 10V, 10mA ≤ I _{OUT} ≤ 1A	-	0.2	5	μΑ
_	Minimum Load Current	3V ≤ (V _{IN} -V _{OUT}) ≤ 15V	_	3.5	10	mA
_	Ripple Rejection	$f = 120$ Hz, $C_{OUT} = 1\mu F$ Tantalum, $(V_{IN}-V_{OUT}) = 3V$, $I_{OUT} = 1A$	60	75	_	dB
_	Temperature Stability	_	_	1	_	%
_	Long-Term Stability	T _A = +125°C, 1000hrs	_	0.3	_	%
_	RMS Output Noise (% of V _{OUT})	T _A = +25°C, 10Hz ≤ f ≤ 10kHz	_	0.003	_	%
		SOT223	_	15	_	
_	Thermal Resistance (Junction to Case)	TO252-2 (1)/TO252-2 (3)	_	10	_	°C/W
(Junction to Case)		T0220-3	_	4.5	_	
_	Thermal Shutdown	Junction Temperature	_	+150	_	°C
_	Thermal Shutdown Hysteresis		_	+25	_	°C

Note 5: Maximum Power Dissipation is Package Type and Case Temperature dependent. Please see Figure Maximum Power Dissipation.

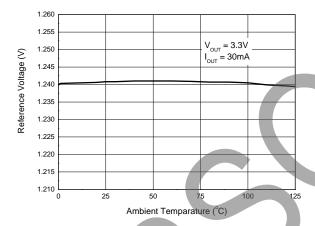


Performance Characteristics

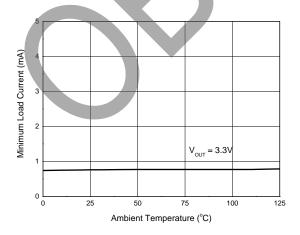
Dropout Voltage vs. Output Current



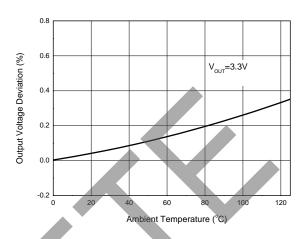
Reference Voltage vs. Temperature



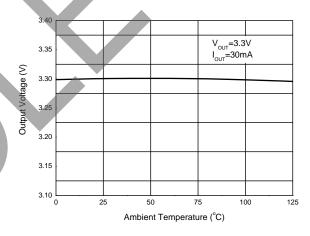
Minimum Load Current vs. Temperature



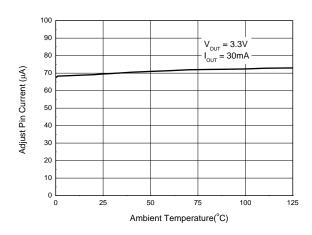
Load Regulation vs. Temperature



Output Voltage vs. Temperature



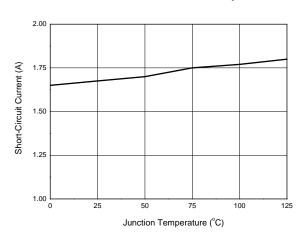
Adjust Pin Current vs. Temperature



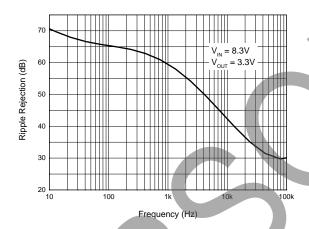


Performance Characteristics (Cont.)

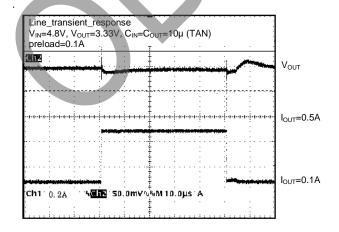
Short-Circuit Current vs. Temperature



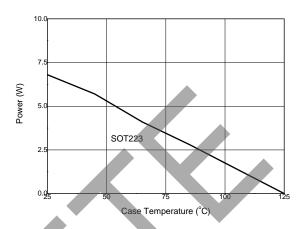
Ripple Rejection vs. Frequency



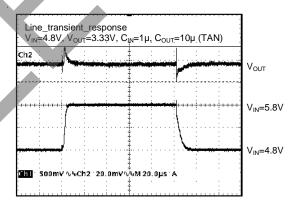
Load Transient Response



Maximum Power Dissipation

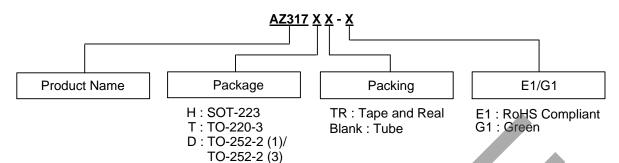


Line Transient Response





Ordering Information







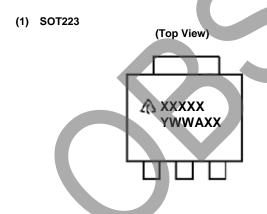




Part Number	Package (Note 7)	Temperature Range	RoHS Compliant / Green	Marking ID	Packing	Quantity	Status (Note 6)
AZ317HTR-E1	SOT223	0 to +125°C	RoHS Compliant	EH31A	Tape & Reel	1000	In Production
AZ317HTR-G1	SOT223	0 to +125°C	Green	GH31A	Tape & Reel	1000	In Production
AZ317T-E1	TO220-3	0 to +125°C	RoHS Compliant	AZ317T-E1	Tube	1000	In Production
AZ317DTR-E1	TO252-2 (1)/(3)	0 to +125°C	RoHS Compliant	AZ317D-E1	Tape & Reel	2500	In Production

6. All variants in TO-263-3 package are End of Life without any replacement.
 AZ317DTR-G1 and AZ317T-G1 are End of Life without any replacement.
 7. For packaging details, go to our website at: https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



First Line: Logo and Marking ID (See Ordering Information)

Second Line: Date Code

Y: Year

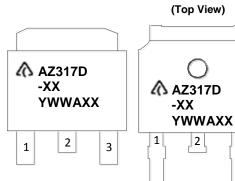
WW: Work Week of Molding A: Assembly House Code

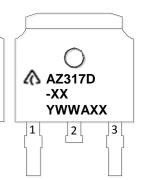
XX: 7th and 8th Digits of Batch Number



Marking Information (Cont.)

(2) TO252-2 (1)/3)





First and Second Lines: Logo and Marking ID (See Ordering Information)
Third Line: Date Code

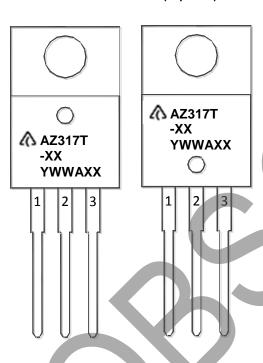
Y: Year

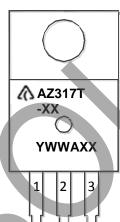
WW: Work Week of Molding

A: Assembly House Code
XX: 7th and 8th Digits of Batch Number



(Top View)





First and Second Lines: Logo and Marking ID (See Ordering Information)
Third Line: Date Code
Y: Year

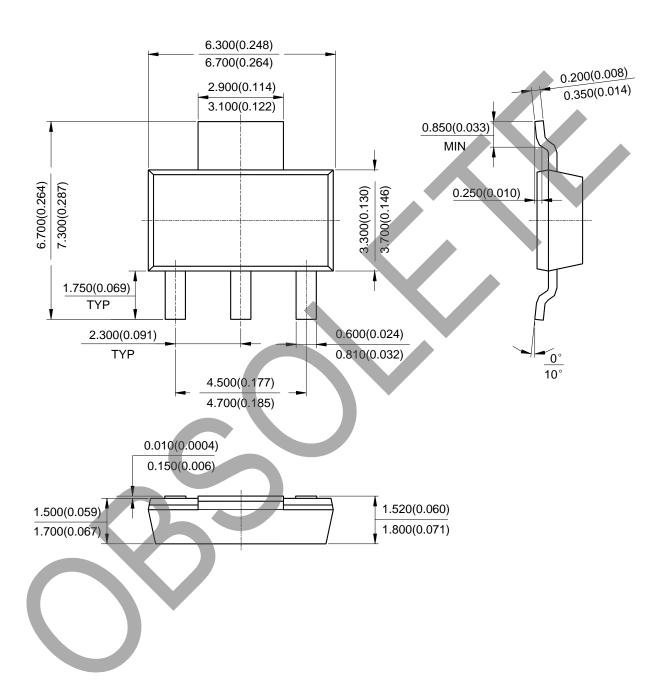
WW: Work Week of Molding A: Assembly House Code

XX: 7th and 8th Digits of Batch Number



Package Outline Dimensions (All dimensions in mm(inch).)

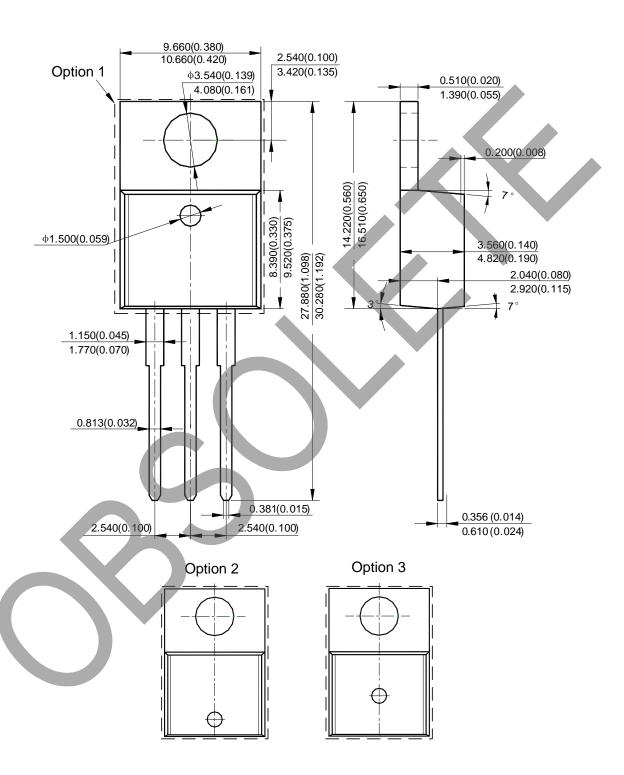
(1) Package Type: SOT223





Package Outline Dimensions (Cont. All dimensions in mm(inch).)

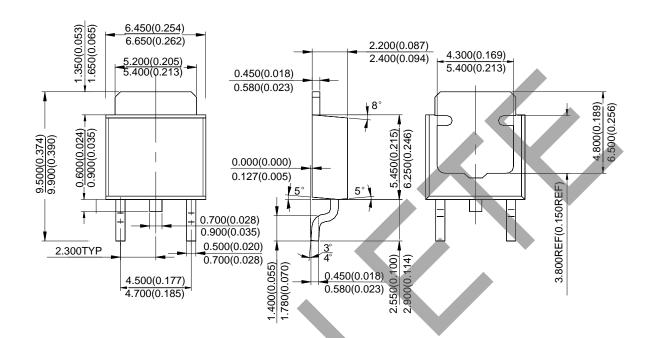
(2) Package Type: TO220-3





Package Outline Dimensions (Cont. All dimensions in mm(inch).)

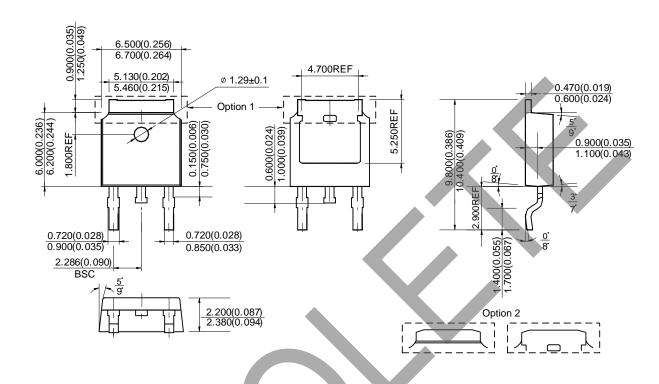
(3) Package Type: TO252-2 (1)





Package Outline Dimensions (Cont. All dimensions in mm(inch).)

(4) Package Type: TO252-2 (3)

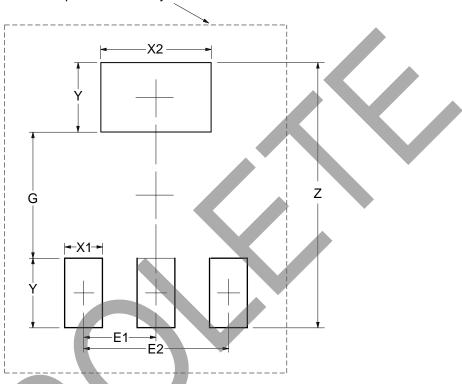




Suggested Pad Layout

(1) Package Type: SOT223



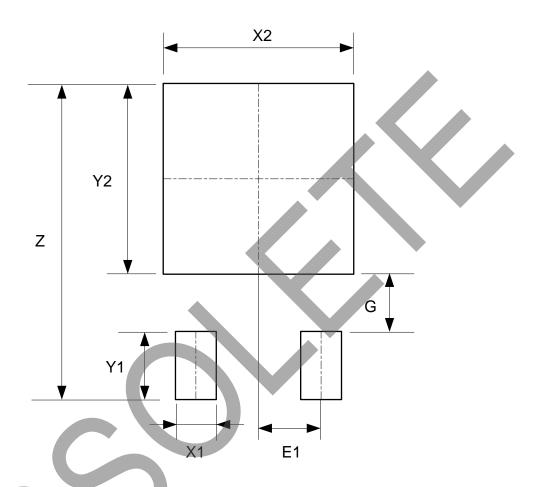


Dimonoiono	Z	G	X1	X2	Υ	E1	E2
Dimensions (mm)/(inch)		(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)
Value	8.400/0.331	4.000/0.157	1.200/0.047	3.500/0.138	2.200/0.087	2.300/0.091	4.600/0.181



Suggested Pad Layout (Cont.)

(2) Package Type: TO252-2 (1)

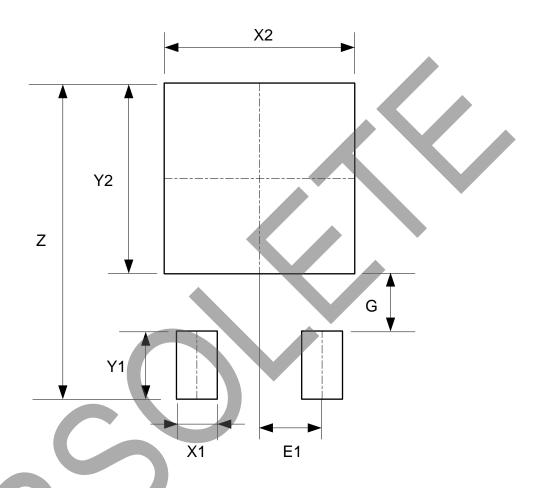


Dimensions	Z	X1	X2=Y2	Y1	G	E1
	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)
Value	11.600/0.457	1.500/0.059	7.000/0.276	2.500/0.098	2.100/0.083	2.300/0.091



Suggested Pad Layout (Cont.)

(3) Package Type: TO252-2 (3)



Dimensions	Z	X1	X2=Y2	Y1	G	E1
	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)
Value	11.600/0.457	1.500/0.059	7.000/0.276	2.500/0.098	2.100/0.083	2.300/0.091



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